



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN20210915000.1A
Qualify additional Assembly sites for select SOT devices
Change Notification / Sample Request

Date: October 28, 2021
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

Revision A is to announce the addition of a new devices that was not included on the original PCN notification.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team ([PCN ww_admin_team@list.ti.com](mailto:PCN_admin_team@list.ti.com)). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team
SC Business Services

20210915000.1A
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LVC1G08DBVR	null
SN74LVC1G125DBVR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20210915000.1A		PCN Date:	October 28, 2021										
Title:	Qualify additional Assembly sites for select SOT devices													
Customer Contact:	PCN Manager	Dept:	Quality Services											
Proposed 1st Ship Date:	Dec 20, 2021	Estimated Sample Availability:	Provided upon Request											
Change Type:														
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site												
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material												
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process												
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site												
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials												
		<input type="checkbox"/> Wafer Fab Process												
PCN Details														
Description of Change:														
<p>Revision A is to announce the <u>addition</u> of new devices that was not included on the original PCN notification. The new devices are listed on the Product Affected section below. The expected first shipment date for the new device will be 90 days from this notice (Jan. 27, 2022) for the newly added device only. The proposed 1st ship date of Dec 20, 2021 still applies for the original set of devices.</p> <p>Texas Instruments Incorporated is announcing the qualification of additional Assembly sites for devices listed below in the product affected section. Construction differences and current assembly sites are as follows:</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th colspan="2">SOT-23 (DBV)</th> </tr> </thead> <tbody> <tr> <td>Assembly Sites</td> <td>TIPI, ASEWH, HFTF, HNA, TFME, TIEM, CDAT</td> </tr> <tr> <td>Lead Finish</td> <td>NiPdAu; NiPdAuAg; Matte Sn</td> </tr> <tr> <td>Mount compound</td> <td>400180 A-03 4213245 400194 4207123</td> </tr> <tr> <td>Mold Compound</td> <td>R-27 8097131 R-13 450413 R-04 450042 4222198</td> </tr> </tbody> </table> <p>Upon expiration of this PCN, TI will combine lead free solutions in a single <u>standard part number</u>, for example; <u>INA193AIDBVR</u>– can ship with both Matte Sn and NiPdAu. When available customers may specify NiPdAu finish by ordering the part with the G4 suffix, e.g. INA193AIDBVRG4.”</p>					SOT-23 (DBV)		Assembly Sites	TIPI, ASEWH, HFTF, HNA, TFME, TIEM, CDAT	Lead Finish	NiPdAu; NiPdAuAg; Matte Sn	Mount compound	400180 A-03 4213245 400194 4207123	Mold Compound	R-27 8097131 R-13 450413 R-04 450042 4222198
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Mount compound	400180 A-03 4213245 400194 4207123													
Mold Compound	R-27 8097131 R-13 450413 R-04 450042 4222198													
Reason for Change:														
Continuity of Supply														
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):														
None														

Impact on Environmental Ratings


Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change


Changes to product identification resulting from this PCN:

Assembly Site		
TI Philippines (TIPI)	Assembly Site Origin (22L)	ASO: PHI
ASEWH	Assembly Site Origin (22L)	ASO: AWH
HFTF	Assembly Site Origin (22L)	ASO: HFT
HNA	Assembly Site Origin (22L)	ASO: HNT
TFME	Assembly Site Origin (22L)	ASO: NFM
TI Chengdu (CDAT)	Assembly Site Origin (22L)	ASO: CDA
TI Melaka (TIEM)	Assembly Site Origin (22L)	ASO: CU6

Sample product shipping label (not actual product label)



TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR SEAL DT
MSL 1 /235C/UNLIM 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)T0:1750



E4/G4: NiPdAu
E3/G3: Matte Sn

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

SN74LVC1G02DBVR	SN74LVC1G08DBVR	SN74LVC1G125DBVR
SN74LVC1G02DBVRG4	SN74LVC1G08DBVRG4	TLV9041UIDBVR

DBV (SOT-23) Qualification Report

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

	Stress Test	Duration	PHI TPS76933DBV	CDAT TLV9061IDBV
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/- (Note a)
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-

	Stress Test	Duration	PHI TPS76933DBV	CDAT TLV9061IDBV
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	TFME SN74AHC1G14DBV	HNA INA293A1IDBV
TC	Temperature Cycling -65/150C	500 Cycles	3/231/0	3/231/0
HAST	Biased HAST 130C/85%RH	96 hours	3/231/0	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	3/231/0	3/231/0
UHA	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0
AC	Autoclave 121C	96 hours	3/231/0	-
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0	3/66/0 (SN74LVC1GU04DBV)
MQ	Manufacturability	-	Pass	Pass

	Stress Test	Duration	TIEMA DAC121S101CIMK	HFTAT TLV70333DBV	ASEWH TL431CDBV
TC	Temperature Cycling -65/150C	500 Cycles	-	3/231/0	3/231/0
TC	Temperature Cycling -55/150C	1000 Cycles	3/231/0	-	-
HAST	Biased HAST 130C/85%RH	96 hours	-	3/231/0	3/231/0
THB	Temperature Humidity Bias 85C/85%RH	1000 hours	3/231/0	-	-
HTSL	High Temp. Storage Bake 150C	1000 hours	3/231/0	-	3/231/0
HTSL	High Temp. Storage Bake 170C	420 hours	-	3/231/0	-
UHA	Unbiased HAST, 130C/85%RH	96 hours	-	3/231/0	-
AC	Autoclave 121C	96 hours	3/231/0	-	3/231/0
SD	Solderability	8 Hour Steam age or 155C Dry Bake	3/66/0 (LM2660MM/NOPB)	3/66/0 (TLV74333PDBV)	3/66/0
MQ	Manufacturability	-	Pass	Pass	Pass

All qualification devices in the tables are qualified at L1-260C MSL rating.

Note a – Data collection in progress. Data will be made available upon request after completion.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, and HTSL, as applicable

- The following are equivalent HTSL options based on activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status: Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

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